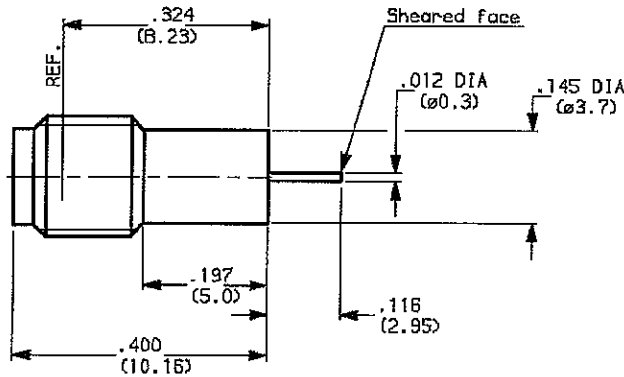


HERMETICALLY SEALED RECEPTACLE
SOLDER IN TYPE

SERIES: SSMA 1 / 2



MOUNTING HOLE

See page 2

5

WEIGHT oz (g)

CHARACTERISTICS

| | |
|---------------------------------|-------------------------------------|
| NOMINAL IMPEDANCE | 50 Ω |
| FREQUENCY RANGE | 0-18 GHz |
| TEMPERATURE RATING | -55/+155 °C |
| VSWR | TBD GHz |
| RF INSERTION LOSS | TBD /F dB Maxi |
| VOLTAGE RATING | 250 Vrms Maxi |
| DIELECTRIC WITHSTANDING VOLTAGE | 750 Vrms mini |
| INSULATION RESISTANCE | 5000 Ma mini |
| HERMETIC SEAL | 10-8 cc/s Atm.cm ³ /s |
| LEAKAGE (pressurized only) | NA psi MPa |
| - | - |
| - | - |

STANDARDISATION

CABLE RETENTION

NA lb mini
N

CENTER CONTACT RETENTION

| | |
|----------------------------|-----------------------|
| Axial force - mating end | 3.955 lb mini |
| Axial force - opposite end | 3.955 lb mini |
| Torque (Min) | NA Inch.oz NA cm.N |

RECOMMENDED TORQUES

| | |
|-----------|-----------------------|
| Mating | NA Inch.Lb NA cm.N |
| Panel nut | NA Inch.Lb NA cm.N |
| Clamp nut | NA Inch.Lb NA cm.N |

CONSTRUCTION

| CONNECTOR PARTS | MATERIALS | FINISH |
|-----------------|----------------------|------------------|
| BODY | STAINLESS STEEL | GOLD OVER NICKEL |
| OUTER CONTACT | - | - |
| CENTER CONTACT | BERYLLIUM COPPER | GOLD OVER NICKEL |
| INSULATORS | PTFE + MATCHED GLASS | - |
| - | - | - |
| - | - | - |
| - | - | - |
| - | - | - |
| - | - | - |

| ISSUE | REVISION No | DESCRIPTION | BY | DATE |
|-------|-------------|-------------------|----------|------|
| C | 0640 | soldering process | B-VACHON | . |
| . | . | . | . | . |
| . | . | . | . | . |
| . | . | . | . | . |

Initiated on 24-01-92

The information given here is subject to change without notice. Design changes may be in order to improve the product.

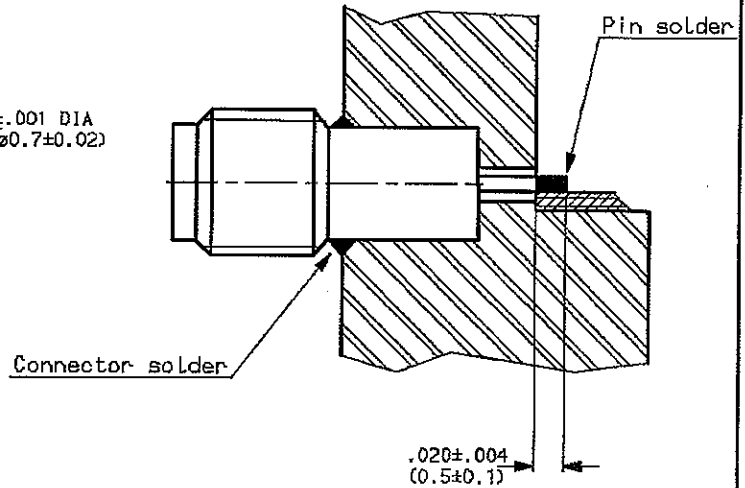
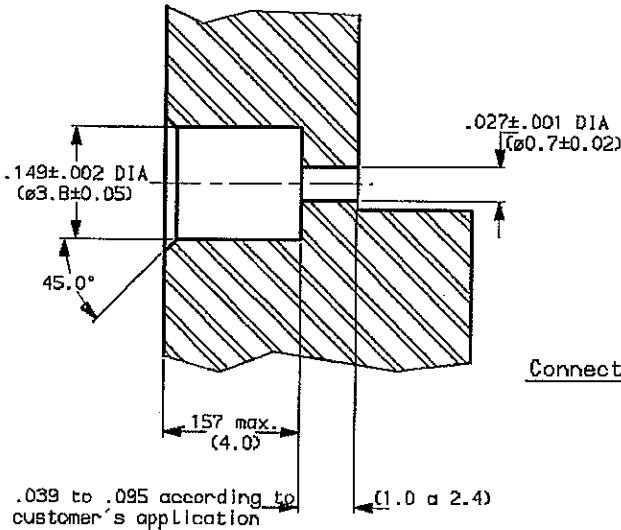


Superseded on

HERMETICALLY SEALED RECEPTACLE
SOLDER IN TYPE

RECOMMENDED MOUNTING HOLE DETAIL

MOUNTING INSTRUCTIONS



- 1 - Degrease and clean connector and box .
- 2 - Solder the connector on the panel :
(Temperature 180°C) - Preheating at about 100°C
Take care not to exceed 250°C during solder operation .
- 3 - Solder the pin on the track :
(Temperature 180°C)
-ceramic substrates : preheating at about 100°C
-other substrates : no preheating required .

NOTE : Please use a small soldering iron, or hot air soldering system .

| ISSUE | REVISION No | DESCRIPTION | BY | DATE |
|-------|-------------|----------------|----------|------|
| C | 0640 | solder process | B VACHON | . |
| . | . | . | . | . |
| . | . | . | . | . |
| . | . | . | . | . |

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Superseded on --- -- --

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